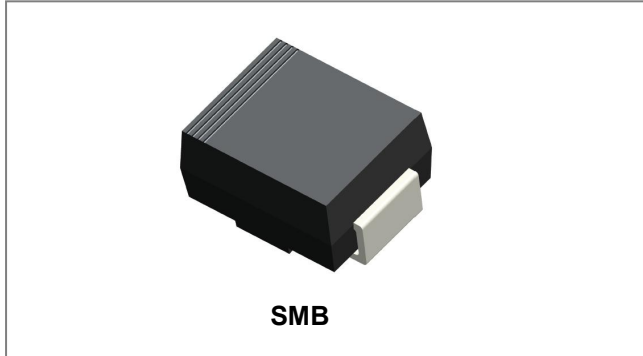


RS2A-RS2M SURFACE MOUNT SUPER FAST RECTIFIER



Features

- Fast switching for high efficiency
- Low leakage current
- High forward surge capability
- Solder dip 260 ° C, 40 s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: SMB molded plastic body
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.09 grams

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Type Number	Symbol	RS2A	RS2B	RS2D	RS2G	RS2J	RS2K	RS2M	Units
Peak Repetitive Reverse Voltage	V _{RRM}								
Working Peak Reverse Voltage	V _{RWM}	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V _{DC}								
RMS Reverse Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Average forward rectified output current @T _A = 90°C	I _O	2.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50							A
Forward Voltage @I _F =2.0A	V _F	1.3							V
Peak Reverse Current @T _A = 25°C	I _{RM}	5.0							μA
At Rated DC Blocking Voltage @T _A = 100°C		50							
Maximum Reverse Recovery Time (Note 1)	T _{rr}	150				250	500		ns
Typical Junction Capacitance (Note 2)	C _J	50							pF
Typical Thermal Resistance (Note 3)	R _{θJA}	55							°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150							°C

Note: 1. Measured with I_F=0.5A, I_R=1.0A, I_{rr}=0.25A,
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 VDC
 3. Thermal resistance from junction to ambient at 0.375"(9.5mm)lead length, P.C.B. mounted

Ratings and Characteristics Curves

FIG.1-FORWARD CURRENT DERATING CURVE

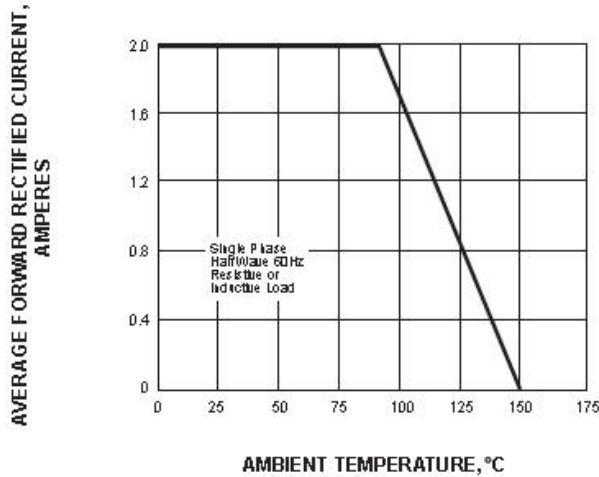


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

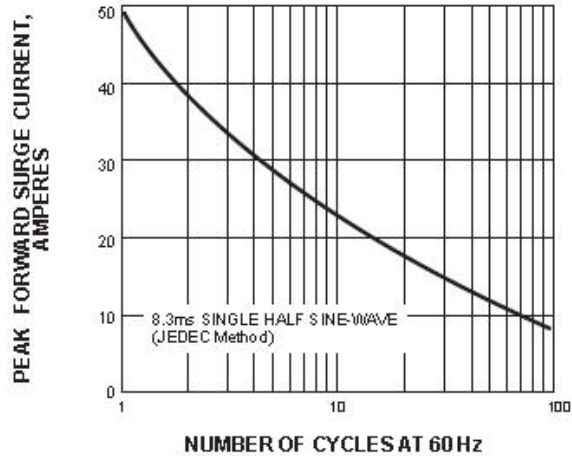


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

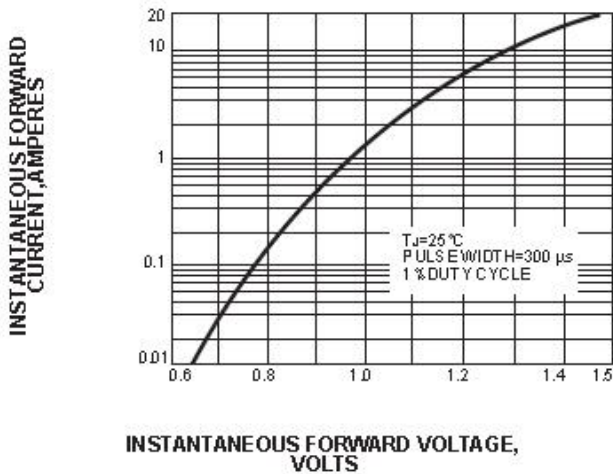
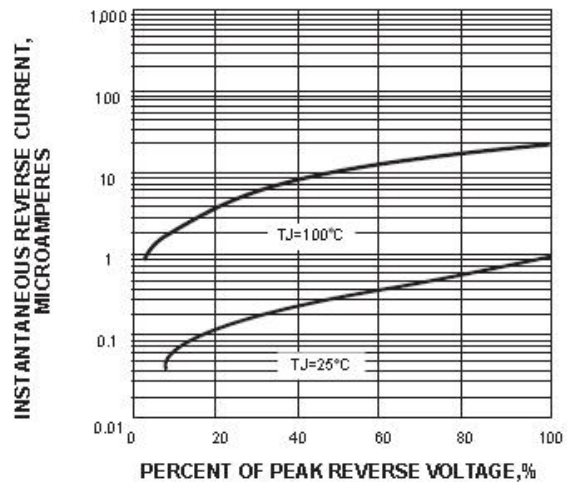
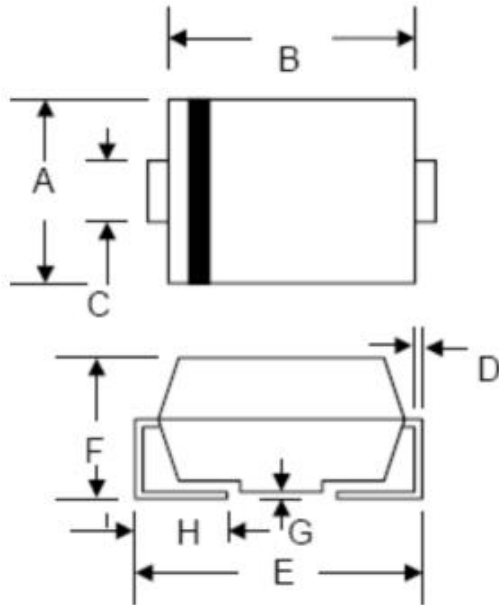


FIG.4-TYPICAL REVERSE CHARACTERISTICS



Mechanical Dimensions SMB



SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	3.94	0.130	0.155
B	4.06	4.70	0.160	0.185
C	1.80	2.20	0.071	0.087
D	0.152	0.305	0.006	0.012
E	4.80	5.59	0.189	0.220
F	2.10	2.60	0.083	0.102
G	0.051	0.203	0.002	0.008
H	0.76	1.52	0.030	0.060

Ordering Information

Device	Package	Shipping
RS2A-RS2M	SMB(Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

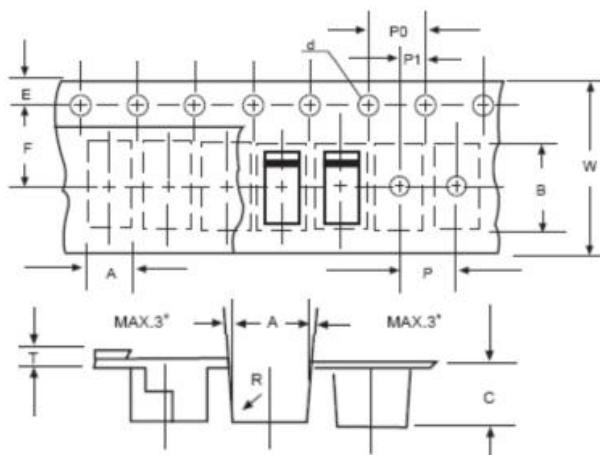


Where XXXXX is YYWWL

RS2A = Type Number
SSG = SSG
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification SMB



SYMBOL	Millimeters	
	Min.	Max.
A	3.99	4.19
B	5.72	5.92
C	3.23	3.43
d	1.40	1.60
E	1.40	1.60
F	5.60	5.70
P	7.90	8.10
P0	3.90	4.10
P1	1.90	2.10
T	-	0.60
W	11.80	12.20

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